

Bill of Materials

TI DESIGNS
TIPD193: RTD to Voltage Reference Design Using Instrumentation Amplifier and Current Reference

Item #	QTY	Value	Designator	Description	Manufacture	Part Number	Supplier Part Number
1	3	0.1uF	C1, C4, C5	CAP, CERM, 0.1 μ F, 25 V, +/- 10%, X5R, 0603	AVX Corporation	06033D104KAT2A	478-1244-1-ND
2	1	220pF	C2	CAP, CERM, 220 pF, 50 V, +/- 5%, C0G/NP0, 0603	Murata Electronics North America	GRM1885C1H221JA01D	490-1435-1-ND
3	1	10uF	C3	CAP, TA, 10 μ F, 50 V, +/- 10%, 0.8 ohm, SMD	Vishay Sprague	293D106X9050E2TE3	718-1022-1-ND
4	2	1000pF	C6, C7	CAP, CERM, 1000 pF, 100 V, +/- 5%, X7R, 0603	AVX Corporation	06031C102JAT2A	478-3698-1-ND
5	1	0.01uF	C8	CAP, CERM, 0.01 μ F, 100 V, +/- 5%, X7R, 0603	AVX Corporation	06031C103JAT2A	478-3700-1-ND
6	1		J1	Screw Terminal, 3 Pos, 3.5mm Spacing, Through Hole	On Shore Technology Inc	ED555/3DS	ED1515-ND
7	1		J2	Screw Terminal, 2 pos, 3.5mm Spacing, Through Hole	On Shore Technology Inc	ED555/2DS	ED1514-ND
8	2		J4, J5	JACK NON-INSULATED .218",Banana Jack	Keystone Electronics	575-4	575-4K-ND
9	1	2k	R1	RES, 2.00 k, 0.1%, 0.063 W, 0603	Vishay Beyschlag	MCT06030C2001FP500	MCT0603-2.00K-CFCT-ND
10	1	698k	R2	RES, 698 k, 1%, 0.1 W, 0603	Vishay Dale	CRCW0603698KFKEA	541-698KHCT-ND
11	1	78.7k	R3	RES, 78.7, 1%, 0.125 W, 0805	Vishay Dale	CRCW080578R7FKEA	541-78.7CCT-ND
12	2	10k	R4, R5	RES, 10 k, 0.1%, 0.063 W, 0603	Vishay Beyschlag	MCT06030C1002FP500	MCT0603-10.0K-CFCT-ND
13	4		TP1, TP3, TP4, TP5	Test Point, TH, Compact, Red	Keystone Electronics	5005	5005K-ND
14	2		TP2, TP6	Test Point, TH, Compact, Black	Keystone Electronics	5006	5006K-ND
15	1		U1	Precision, Rail-to-Rail I/O INSTRUMENTATION AMPLIFIER, VSSOP-8	Texas Instruments	INA326EA	INA326EA/2K5CT-ND
16	1		U2	IC CURR SOURCE/SINK MIRROR 8SOIC	Texas Instruments	REF200	296-27726-1-ND
17	4			STANDOFF HEX 4-40THR ALUM 1L"		Keystone Electronics	2205K-ND
18	4			MACHINE SCREW PAN PHILLIPS 4-40		B&F Fastener Supply	H703-ND

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